Amendments to the Claims

1–9. (Cancelled).

10. (New) A method of gluing a circuit component to a circuit board comprising:

placing a plurality of adhesive dots in a regular pattern in the contact area between the circuit component and the circuit board;

placing one or more fore-running adhesive dots in the contact area and not in alignment with the regular pattern of adhesive dots; and

contacting the circuit component and the circuit board such that the fore-running adhesive dots merge with the regular patterned adhesive dots.

11. (New) The method of claim 10 wherein at least two fore-running adhesive dots are placed along a line.

12. (New) The method of claim 10 wherein the line along which the first adhesive dot is placed comprises a central longitudinal axis of the contact area.

13. (New) The method of claim 10 wherein the regular pattern comprises rows and columns, and wherein one fore-running adhesive dot is aligned with a central column of regular patterned adhesive dots.

14. (New) The method of claim 13 wherein one or more fore-running adhesive dots are staggered between columns of regular patterned adhesive dots.

15 (New) The method of claim 10 wherein, upon contacting the circuit component and the circuit board, one or more fore-running adhesive dots merge with one or more regular patterned adhesive dots prior to regular patterned adhesive dots merging with other regular patterned adhesive dots.

16 (New) The method of claim 10 wherein the adhesive of the merged fore-running adhesive dots and regular patterned adhesive dots displaces air through the interstitial spaces of non-merged regular patterned adhesive dots to prevent trapped air pockets between the circuit component and the circuit board.

17 (New) The method of claim 10 wherein the one or more fore-running adhesive dots are placed in the contact area before any regular patterned adhesive dots are placed in the contact area.

18. (New) The method of claim 1 wherein the total amount of adhesive in the fore-running adhesive dot is less than about 10% of the total amount of adhesive in the regular patterned adhesive dots.

19 (New) The method of claim 10 wherein at least one fore-running adhesive dot comprises more adhesive than any regular patterned adhesive dot.

20. (New) The method of claim 10 further comprising placing a corner adhesive dot adjacent a corner of the contact area.

21. (New) The method of claim 20 wherein the corner of the regular pattern corresponds to a corner of the circuit component, and wherein placing the corner adhesive dot comprises placing the corner adhesive dot on a bisectrix of the corner of the contact area.

22. (New) The method of claim 20 wherein the distance between the corner adhesive dot and an adjacent edge of the contact area is less than the distance between any regular patterned adhesive dot and the adjacent edge of the contact area.

23. (New) The method of claim 10 wherein the total amount of adhesive in the regular patterned adhesive dots generates an adhesive layer between about 2μm and about 10μm. after contacting the circuit component and the circuit board.

24. (New) The method of claim 23 wherein the adhesive layer is about 5μm thick.

25. (New) The method of claim 10 wherein the adhesive comprises an epoxy resin that includes metal particles.

26. (New) The method of claim 10 wherein placing adhesive dots comprises flowing adhesive through a nozzle.